



200V N-Channel Trench Power MOSFET

General Description

The SJA02N5000 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a wide variety of applications.

Features

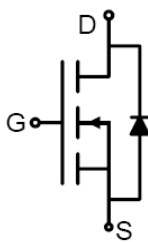
- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handling capability
- Lead free product is acquired

Application

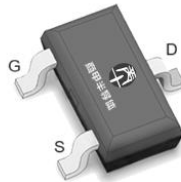
- PWM Applications
- Load Switch
- Power Management

Key Performance Parametes

Parameter	Value	Unit
V_{DS}	200	V
$R_{DS(ON_TYP)}$	505	mΩ
I_D	1.24	A
Q_G	16.8	nC



Schematic Diagram



SOT-23-3L top view



Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Reel Size	Tape width	Quantity
SJA02N5000	2001	SOT-23-3L			

Table 1. Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	200	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	± 20	V
I_D	Drain Current-Continuous($T_A=25^\circ\text{C}$)	1.24	A
	Drain Current-Continuous($T_A=100^\circ\text{C}$)	0.8	A
I_{DM} (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	5.2	A
P_D	Maximum Power Dissipation($T_A=25^\circ\text{C}$)	2.4	W
	Maximum Power Dissipation($T_A=100^\circ\text{C}$)	1	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	$^\circ\text{C}$

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		52	$^\circ\text{C}/\text{W}$



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Table 3. Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	200			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =200V, V _{GS} =0V			1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1		3	V
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =2A		8		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =1A		505	606	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f=1.0MHz		742		pF
C _{oss}	Output Capacitance			14		pF
C _{rss}	Reverse Transfer Capacitance			5		pF
Switching Parameters						
t _{d(on)}	Turn-on Delay Time	V _{GS} =10V, V _{DS} =100V, R _L =50Ω, R _{GEN} =2.5Ω		10		nS
t _r	Turn-on Rise Time			13		nS
t _{d(off)}	Turn-Off Delay Time			16		nS
t _f	Turn-Off Fall Time			14		nS
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =100V, I _D =2A		16.8		nC
Q _{gs}	Gate-Source Charge			2.4		nC
Q _{gd}	Gate-Drain Charge			6.8		nC
Source-Drain Diode Characteristics						
I _{SD}	Source-Drain Current (Body Diode)				1.24	A
V _{SD}	Forward on Voltage ^(Note 2)	V _{GS} =0V, I _S =1A			1.2	V

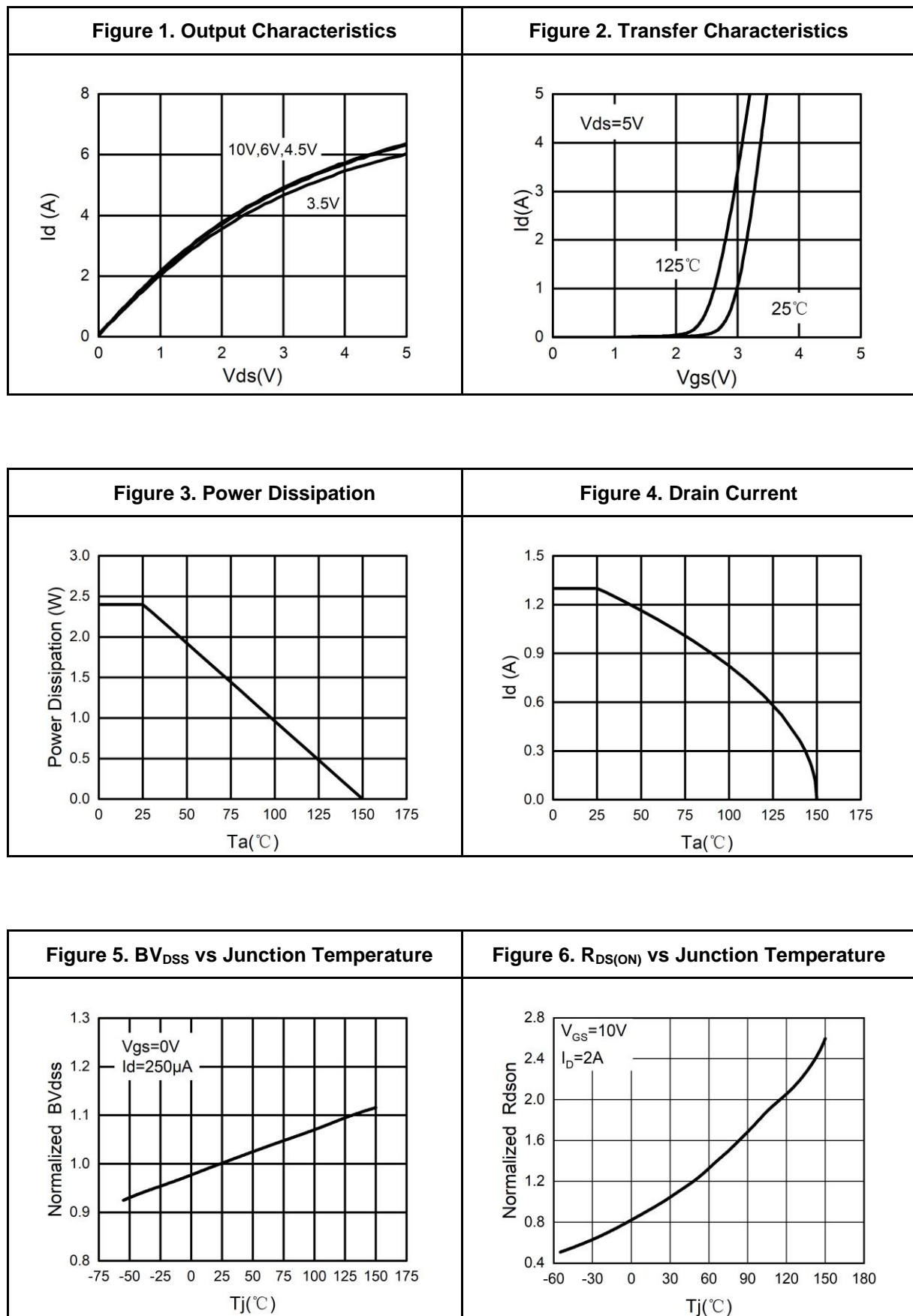
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

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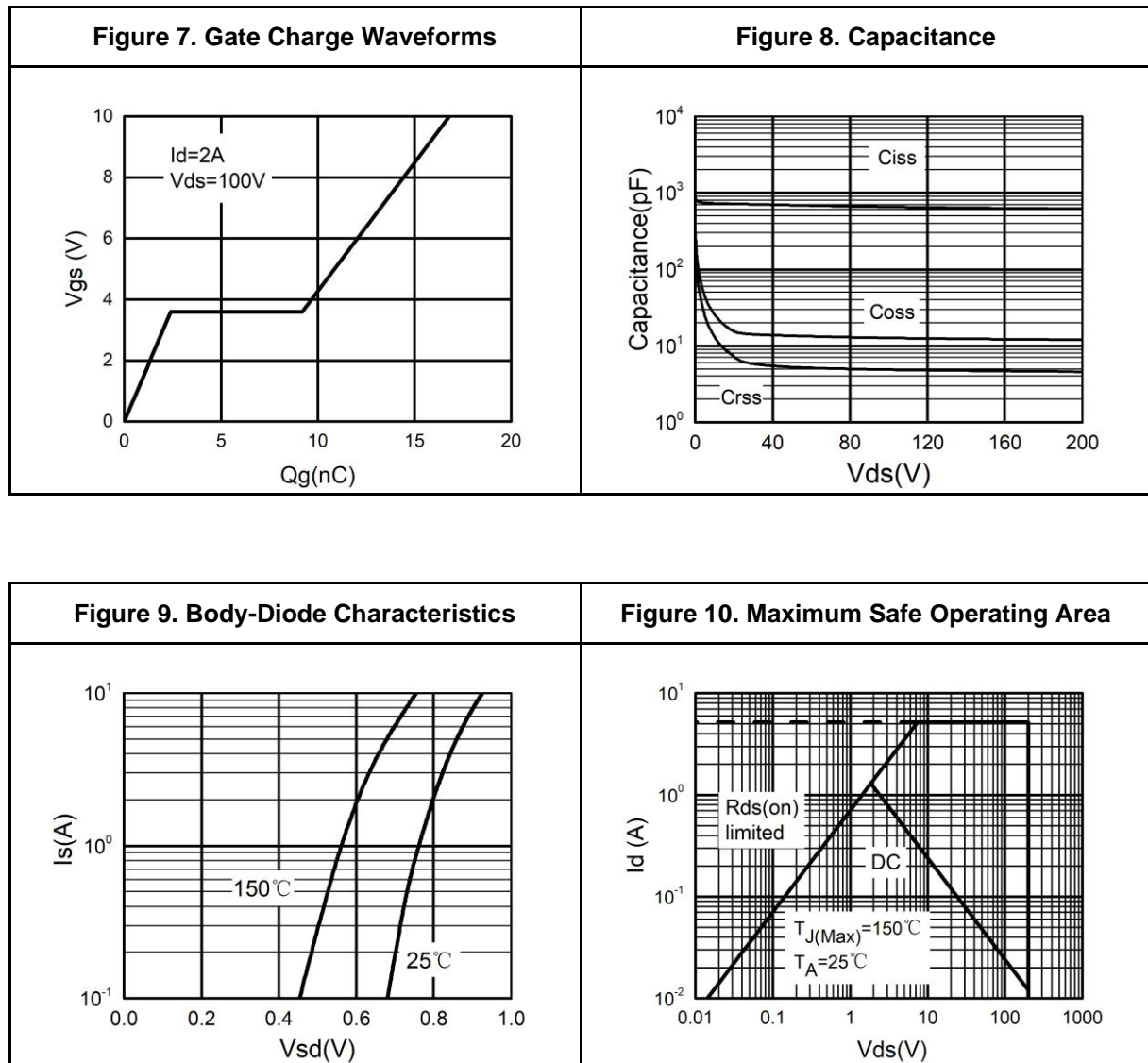
Typical Electrical And Thermal Characteristics (Curves)





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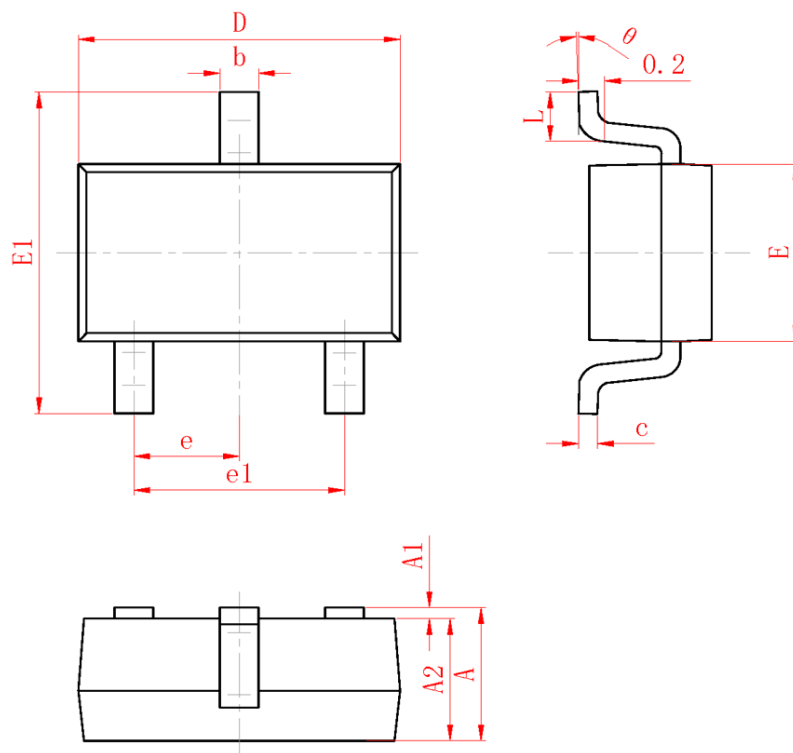
Typical Electrical And Thermal Characteristics (Curves)





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SOT-23-3L Package Information



SYMBOL	MILLIMETER	
	MIN	MAX
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.250	0.450
c	0.100	0.200
D	2.820	3.020
E	1.500	1.700
E1	2.650	2.950
e	0.950 (BSC)	
e1	1.800	2.000
L	0.300	0.500
θ	0°	8°

Symbol	Dimensions In Millimeters	
	Min.	Max.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.250	0.450
c	0.100	0.200
D	2.820	3.020
E	1.500	1.700
E1	2.650	2.950
e	0.950(BSC)	
e1	1.800	2.000
L	0.300	0.500
θ	0°	8°



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